

own, G.A. Dixit, S. Poarh, K. Hamamoto, B. Bohannon, W.Y. Hsu, and R.H. Havemann, *Proc. VLSI Multilevel Interconnection Conf.* (1995) p. 537.

28. Z. Shterenfeld-Lavie, I. Rabinovich, J. Levy, A. Haim, C. Dobson, K. Buchanan, P. Rich, and D.J. Thomas, *Proc. VLSI Multilevel Interconnection Conf.* **31** (1995).

29. H.J. Barth, M. Frank, S. Rohl, M. Schneegans, H. Wendt, C.D. Dobson, P. Rich, K.E. Buchanan, and M.G.M. Harris, *Proc. VLSI Multilevel Interconnection Conf.* **52** (1995).

30. J.R. Black, *IEEE Transactions on Electron Devices*, ED-16 (1969) p. 338.

31. K. Kikuta and T. Kikkawa, *Extended Abstract of the 53rd Autumn Meeting*, vol. 2 (The Japan Society of Applied Physics, 1992) p. 586.

32. M. Hosaka, T. Hosoda, and S. Okamura, *Extended Abstract of the 40th Spring Meeting*, vol. 2 (The Japan Society of Applied Physics and Related Societies, 1993) p. 720.

33. T. Ohba, *Proc. Advanced Metallization for ULSI Applications* (Mater. Res. Soc., Pittsburgh, 1991) p. 25.

34. J.J. Etabil, H.S. Rathore, and E.N. Lavine, *Proc. VLSI Multilevel Interconnection Conf.* (IEEE, New York, 1991) p. 242. □

Advertisers in This Issue	
	Page No.
* Academic Press, Inc.	84
* Aldrich Chemical Co.	28
* A&N Corp.	10
Atomerig Chemetals Corp.	41
Arizona State University	69
* Bede Scientific	18
* BIOSYM/Molecular Simulations	25
* Cambridge University Press	85
* Chemat Technology, Inc.	89
* Commonwealth Scientific Corp.	17
* Digital Instruments	1
Eagle Picher	6
* E S Microware	100
* Elchema	19
* Elsevier Science	14, 30, 83, 104
* Fisons Instruments Surface Systems	9
* Gordon and Breach Publishing Group	87
* High Voltage Engineering	
Europa BV	inside front cover
* Hitachi Scientific Instruments	7
* Huntington Laboratories	outside back cover
* JEOL USA, Inc.	24
Leica, Inc.	12
* Magnet Sales & Manufacturing, Inc.	60
* Maxtek, Inc.	64, 73
* MDC Vacuum Products Corp.	31
* Media Cybernetics	16
* MKS Instruments, Inc.	2
Morton Advanced Materials	11
* Nanophase Technologies Corp.	45
* National Electrostatics Corp.	15
* New Focus, Inc.	inside back cover
* Oxford Instruments	101
* Philips Analytical X-Ray BV	23
* Philips Electron Optics	26
* Plasma Sciences, Inc.	8
* Plenum Publishing Corp.	56, 82
* Princeton Gamma-Tech, Inc.	32
* Quantum Design	52
* Quesant Instrument Corp.	97
* Rigaku/USA, Inc.	96
* Semiconductor Processing Co.	99
* Siemens	105
* Springer-Verlag New York, Inc.	86
* Staib Instruments, Inc.	94
* Sycon Instruments, Inc.	103
* Tencor Instruments	98
* Virginia Semiconductor, Inc.	77, 93
VLSI Standards, Inc.	102
* Voltaix, Inc.	20

For free information about the products and services offered in this issue, fill out and mail the Reader Service Card, or FAX it to (312) 922-3165.

\* Exhibiting at the MRS Fall Meeting

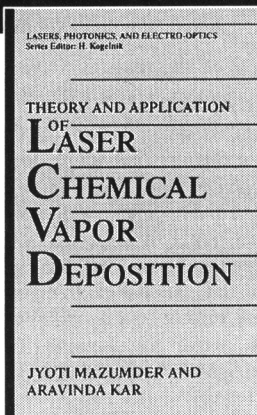
## Discover invaluable new resources from Plenum Press!

### THEORY AND APPLICATION OF LASER CHEMICAL VAPOR DEPOSITION

by Jyoti Mazumder, *University of Illinois*, and Aravinda Kar, *University of Central Florida*

Thoroughly explores the principles of the physico-chemical phenomena involved in Laser Chemical Vapor Deposition (LCVD). Demonstrates their application to developing theories about the assorted types of LCVD processes and to designing and controlling a LCVD system in an optimum way. A volume in the series Lasers, Photonics, and Electro-Optics.

0-306-44936-6/392 pp. + index/ill/1995/\$89.50  
text adoption price on orders of six or more copies: \$49.50 each



### SEMICONDUCTOR ALLOYS

#### Physics and Materials Engineering

by An-Ban Chen, *Auburn University*, and Arden Sher, *SRI International*

The first *comprehensive* treatment of semiconductor alloy properties. Coverage includes • atomic arrangements • bonding • elasticity • alloy statistics and phase diagrams • band structures • optical properties • and electronic transport. Features review problems, extensive tables and figures, and end-of-chapter comments. A volume in the series Microdevices: Physics and Fabrication Technologies.

0-306-45052-6/339 pp. + index/ill/1995/\$79.50  
text adoption price on orders of six or more copies: \$42.50 each

### JOURNAL OF MICROELECTRONIC SYSTEMS INTEGRATION

Editor: Stuart K. Tewksbury, *West Virginia University*

Publishes current research on system integration issues valuable for microelectronics specialists and systems engineers. Contributions cover case studies of high performance microelectronic system prototypes and advanced products; theories and analytic models; and fundamentals of technology for microelectronic systems.

Subscription: Volume 4, 1996 (4 issues)  
Institutional rate: \$175.00 in US/\$205.00 elsewhere  
Personal rate: \$53.00 in US/\$62.00 elsewhere

Book prices are 20% higher outside US & Canada.



233 Spring Street, New York, NY 10013-1578  
Telephone orders: 212-620-8000/1-800-221-9369

**Stop by the Plenum booth (#109) at the MRS meeting for a free sample copy of this journal and ask about our special conference discounts!**

Circle No. 40 on Reader Service Card.